



Note:

1. Material:

- 1.1 Housing: LCP GLASS FIBRE, UL94v-0
- 1.2 Contact-1: copper alloy, C5191 T=0.20mm
- 1.3 Contact-2: copper alloy, SUS304 T=0.40mm
- 1.4 Shell: copper alloy, C2680 T=0.20mm

2. Specification:

- 2.1 Current rating: 2A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kg Max.
- 2.6 Total unmating force: 1.0 Kg Min. 0.81~2.05 Kg Min. after 10000 insertion/extraction cycles
- 2.7 Temperature range:  $-30^{\circ}\text{C} \sim 80^{\circ}\text{C}$

3. Plating:

- 3.1 SHELL: Nickel Plating  $80\mu\text{m} \sim 120\mu\text{m}$
- 3.2 CONTACT: Nickel Base  $50\mu\text{m}$  Tin Plating  $100\mu\text{m}$

<p><b>RoHS Compliant</b></p>		<p><b>HSM</b> 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.</p>											
				<p>TOLERANCE 容許公差</p> <table border="1"> <tr> <td>X</td> <td><math>\pm 0.15</math></td> <td>X*</td> <td><math>\pm 0.25</math></td> </tr> <tr> <td>X</td> <td><math>\pm 0.12</math></td> <td>X*</td> <td><math>\pm 0.20</math></td> </tr> <tr> <td>XX</td> <td><math>\pm 0.08</math></td> <td>XX*</td> <td><math>\pm 0.15</math></td> </tr> </table>		X	$\pm 0.15$	X*	$\pm 0.25$	X	$\pm 0.12$	X*	$\pm 0.20$
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APPD. 核准	SCALE 比例	UNIT 單位	PART NAME 品名										
DWG. 製圖	Hedy	M M	MICRO USB A Type 5P MALE SOLDER TYPE NICKEL SHELL SELECTIVE GOLD PLATING BLACK INSULATOR HOSUING MATERIAL: LCP ROHS										
DATE 制表日	2018/11/13	PAGE 張數	PART NO. 料號										
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